

BIN ZHAO



BIOGRAPHY: Bin Zhao received his Ph.D. degree from California Institute of Technology and has held engineering and management positions at SEMATECH, Rockwell, Conexant, Skyworks, Freescale, Fairchild, and ON Semiconductor. He has worked on advanced VLSI technology development and design implementation of analog/mixed-signal, power management, and RF IC products. In 1997, he fabricated the industry-first Cu/low-k ($k < 3$) dual-damascene interconnect by developing a successful fabrication process for the Cu/SiOCH low-k dual-damascene interconnect, which is widely used in today's high-performance IC products. He has authored and coauthored more than 200 journal publications and conference presentations, has written three book chapters, and holds more than 70 issued US patents. He is an IEEE Fellow and served as the Founding Co-Chair of the Technical Working Group of RF and Analog/Mixed-Signal IC Technologies for Wireless Communications, the International Technology Roadmap for Semiconductors (ITRS), 2003-2007.

IEEE ACTIVITIES:

COMMITTEES/BOARDS:

- Chair, IEEE Conference Committee, 2019-2022
- Chair, IEEE Conference Governance and Strategy Committee, 2019-2022
- Chair, IEEE Conference Open Access Ad Hoc Committee, 2019-2022
- Chair, IEEE Conference Governance Ad Hoc Committee, 2018
- Chair, IEEE Conference Strategy Ad Hoc Committee, 2017-2018
- Chair, IEEE Future of Conference IP Committee, 2015-2017
- Chair, IEEE Conference Quality Policies Ad Hoc Committee, 2017
- Chair, IEEE Technical Program Integrity Committee, 2013-2014
- Chair, IEEE Reynold B. Johnson Technology Award Committee, 2007-2008
- IEEE Technical Activities Board, 2019-2022
- IEEE TAB Finance Committee, 2019-2022
- IEEE Publications Services and Products Board, 2019-2022
- IEEE Conference Quality Committee, 2017-2018
- IEEE Conference Publication Committee, 2015-2018
- IEEE Technical Program Integrity Committee, 2011-2012
- PSPB Liaison, IEEE Conference Committee, 2015-2016
- TAB Rep, IEEE Conference Committee, 2011-2014
- TAB Rep, IEEE Conference Publication Committee, 2011-2014
- IEEE Fellow Committee, 2012

SOCIETY:

- Treasurer, IEEE Electron Devices Society (EDS), 2020-2021
- Board of Governors, IEEE Electron Devices Society, 2010-2015, 2017-2019
- EDS Vice President of Publications and Products, 2014-2015
- EDS Vice President of Meetings and Conferences, 2010-2013
- Chair, EDS Finance Committee, 2020-2021
- Chair, EDS Publications and Products Committee, 2014-2015
- Chair, Paul Rappaport Award Selection Committee, 2014-2015

- Chair, George E. Smith Award Selection Committee, 2014-2015
- Chair, EDS Conference Committee, 2010-2013
- Chair, EDS VLSI Technology and Circuits Committee, 2004-2009
- EDS VLSI Technology and Circuits Committee, 2003, 2010-2017
- EDS Fellow Committee, 2016-2017
- EDS Executive Committee, 2010-2015, 2020-2021
- EDS Publication Committee, 2004-2013
- EDS Finance Committee, 2010-2015

CONFERENCES:

- General Co-Chair, IEEE International Conference on Solid-State and Integrated-Circuit Technology (ICSICT), 2018, 2020, 2022
- Conference Steering Committee (2020), International Advisory Committee Vice Chair (2018), Emerging Technologies Chair (2017), IEEE Electron Devices Technology and Manufacturing (EDTM) Conference
- Co-Chair, Technical Program Committee, IEEE International Conference on ASIC (ASICON), 2007, 2009, 2011, 2017, 2019, 2021
- Co-Chair, Technical Program Committee, IEEE International Conference on Solid-State and Integrated-Circuit Technology (ICSICT), 2010, 2014, 2016
- Co-Chair, Organizing Committee, International Conference on Solid-State and Integrated-Circuit Technology (ICSICT), 2001, 2004, 2006, 2008
- Technical Program Committee, IEEE Symposium on VLSI Circuits, 2005-2007
- Technical Program Committee, IEEE Symposium on VLSI Technology, 2001-2004
- Chair, Technical Program Subcommittee, Integrated Circuits and Manufacturing, IEEE International Electron Device Meeting (IEDM), 2001
- Technical Subcommittee, Integrated Circuits and Manufacturing, IEDM, 1999-2000
- IEDM Short Course Organizer/Speaker, "More-than-Moore: Technologies for Functional Diversification," December 14, 2008
- IEDM Short Course Organizer/Speaker, "RF Device Technologies for Communication Systems," December 8, 2002

OTHER:

- Chair, Editorial Steering Committee, IEEE Journal of Microelectromechanical Systems (J-MEMS), 2014-2015
- Chair, EiC Search Committee, IEEE Transactions on Electron Devices, 2015
- Chair, EiC Search Committee, IEEE Electron Device Letters, 2015
- Editorial Oversight Committee, IEEE/TMS J. of Electronic Materials, 2014-2016
- Guest Editor, "Special Issue on Device Technologies and Circuit Techniques for Power Management," IEEE Transactions on Electron Devices, 2008
- Guest Editor, "Special Issue on RF Integrated Circuits Technologies," IEEE Transactions on Electron Devices, 2005
- Associate Editor, IEEE Trans on Circuits and Systems, I: Regular Papers, 2006-2007
- Associate Editor, IEEE Trans on Circuits and Systems, II: Express Briefs, 2004-2005
- Guest Editor, "Special Issue on Advances in Interconnect and Packaging Materials," J. of Electronic Materials, 2001